IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	ŧ	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
Supplier	Information														
Company name* Company unique ID				nique ID	ID Unique ID			ique ID Authority				Response Date*			
nsemi												2024-05-15			
Contact Na	ime	Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-E	nv-Stewards		Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number M		Mfr Item Number Mfr Item Name				Effective Date	Versio	Version Manuf		nfacturing Site W		eight*	UOM	Unit Type
		CAT5241YI-50-T2 DPP NV, QUAD 64		64 TAPS, I2C		2024-05-15	TH6			78	3.25	mg	Each		
Ianufac	turing Proccess Informa	ation													·
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		-STD-020 MSL	Rating	Peak Process Body Temperat		Temperatur	ure Max Time at Peak Temperat		Temperatu	re Numb	er of Reflow Cyo	eles
Matte Tin (Sn) - annealed			CU Alloy 1			260	C		30		seconds 3				
omments															
<u>vel 1 - ma</u>	ximum time at peak temperat	ure during sol	ldering is 10	30 seconds											
or more ii	nformation regarding materia	l composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a							
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.62	mg	Supplier	Silicon (Si)	7440-21-3		4.62	mg
Die Attach	0.57	mg	Supplier	Silver (Ag)	7440-22-4		0.4275	mg
			Supplier	Epoxy resins	129915-35-1		0.1425	mg
Lead Frame	23.33	mg	Supplier	Silver (Ag)	7440-22-4		0.7839	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.035	mg
			Supplier	Silicon (Si)	7440-21-3		0.1516	mg
			В	Nickel (Ni)	7440-02-0		0.6999	mg
			Supplier	Copper (Cu)	7440-50-8		21.6596	mg
Mold Compound-Black	46.99	mg		Epoxy Phenol Resin	proprietary data		4.9339	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.056	mg
Plating	2.15	mg	Supplier	Tin (Sn)	7440-31-5		2.15	mg
Wire Bond - Au	0.59	mg	Supplier	Gold (Au)	7440-57-5		0.59	mg